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## FDN86246 N-Channel PowerTrench<sup>®</sup> MOSFET 150 V, 1.6 A, 261 m $\Omega$

### Features

- Max r<sub>DS(on)</sub> = 261 mΩ at V<sub>GS</sub> = 10 V, I<sub>D</sub> = 1.6 A
- Max  $r_{DS(on)}$  = 359 m $\Omega$  at V<sub>GS</sub> = 6 V, I<sub>D</sub> = 1.4 A
- High performance trench technology for extremely low r<sub>DS(on)</sub>
- High power and current handling capability in a widely used surface mount package
- Fast switching speed
- 100% UIL tested
- RoHS Compliant

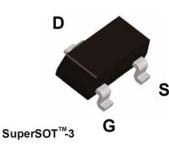


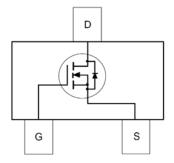
### **General Description**

This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced Power Trench<sup>®</sup> process that has been optimized for  $r_{DS(on)}$ , switching performance and ruggedness.

### Application

PD Switch





### MOSFET Maximum Ratings T<sub>A</sub> = 25 °C unless otherwise noted

Symbol	Parameter		Ratings	Units
V <sub>DS</sub>	Drain to Source Voltage		150	V
V <sub>GS</sub>	Gate to Source Voltage		±20	V
I <sub>D</sub>	-Continuous	(Note 1a)	1.6	Α
	-Pulsed		6	
E <sub>AS</sub>	Single Pulse Avalanche Energy	(Note 3)	13	mJ
P <sub>D</sub>	Power Dissipation	(Note 1a)	1.5	
	Power Dissipation	(Note 1b)	0.6	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temperature Range		-55 to +150	°C

### **Thermal Characteristics**

$R_{ ext{ heta}JC}$	Thermal Resistance, Junction to Case	(Note 1)	75	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	80	C/VV

### Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
246	FDN86246	SSOT-3	7 "	8 mm	3000 units

December 2010

Cteristics Drain to Source Breakdown Voltage Breakdown Voltage Temperature Coefficient Zero Gate Voltage Drain Current Gate to Source Leakage Current	$I_D = 250 \ \mu A, V_{GS} = 0 \ V$ $I_D = 250 \ \mu A, referenced to 25 °C$	150			
Breakdown Voltage Temperature Coefficient Zero Gate Voltage Drain Current Gate to Source Leakage Current	$I_D = 250 \ \mu$ A, referenced to 25 °C	150			
Breakdown Voltage Temperature Coefficient Zero Gate Voltage Drain Current Gate to Source Leakage Current	$I_D = 250 \ \mu$ A, referenced to 25 °C				V
Gate to Source Leakage Current	1/2 - 120 1/2 / - 0 1/2		106		mV/°C
	V <sub>DS</sub> = 120 V, V <sub>GS</sub> = 0 V			1	μA
4	V <sub>GS</sub> = ±20 V, V <sub>DS</sub> = 0 V			±100	nA
Cteristics (Note 2)					
	tate to Source Threshold Voltage $V_{GS} = V_{DS}$ , $I_D = 250 \ \mu A$		3.4	4	V
Gate to Source Threshold Voltage	$I_D = 250 \ \mu\text{A}$ , referenced to 25 °C	2	-9	-	mV/°C
· · · · · · · · · · · · · · · · · · ·	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 1.6 A		195	261	
Static Drain to Source On Resistance			242	359	mΩ
	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 1.6 A, T <sub>J</sub> = 125 °C		359	481	-
Forward Transconductance	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1.6 A		4		S
Characteristics				r	1
			168	225	pF
				30	pF
	f = 1 MHz		1.6	5	pF
Gate Resistance			0.9		Ω
Characteristics		L	l		1
			4.5	10	ns
					ns
					ns
			-		ns
	$V_{cc} = 0 V to 10 V$		-	-	nC
iotal oato onalgo			1.6	3	nC
Total Gate Charge	$V_{CS} = 0 \times 10 5 \times 10^{-5} = 15 \times 10^{-5}$		-	-	-
Total Gate Charge Gate to Source Gate Charge	$V_{GS} = 0 V \text{ to } 5 V$ $V_{DD} = 75 V,$ $I_{D} = 1.6 A$		0.9		nC
Gate to Source Gate Charge	$V_{GS} = 0.0050$ $V_{DD} = 750$ , $I_D = 1.6 A$		0.9 0.8		nC nC
Gate to Source Gate Charge Gate to Drain "Miller" Charge	$V_{GS} = 0.0 \text{ to } 5.0 \text{ V}_{DD} = 75 \text{ V},$ $I_D = 1.6 \text{ A}$				-
Gate to Source Gate Charge Gate to Drain "Miller" Charge rce Diode Characteristics	I <sub>D</sub> = 1.6 A		0.8	1.3	-
Gate to Source Gate Charge Gate to Drain "Miller" Charge	$V_{GS} = 0 V to 5 V V_{DD} = 75 V,$ $I_{D} = 1.6 A$ $V_{GS} = 0 V, I_{S} = 1.6 A (Note 2)$ $I_{F} = 1.6 A, di/dt = 100 A/\mu s$			1.3 70	nC
	Temperature Coefficient Static Drain to Source On Resistance Forward Transconductance Characteristics Input Capacitance Output Capacitance Reverse Transfer Capacitance	Temperature CoefficientID $= 250 \ \mu$ A, referenced to $25 \ ^{\circ}$ CStatic Drain to Source On Resistance $V_{GS} = 10 \ V, ID = 1.6 \ A$ $V_{GS} = 6 \ V, ID = 1.4 \ A$ VGS $= 10 \ V, ID = 1.6 \ A, TJ = 125 \ ^{\circ}$ CForward Transconductance $V_{DS} = 10 \ V, ID = 1.6 \ A, TJ = 125 \ ^{\circ}$ CForward Transconductance $V_{DS} = 10 \ V, ID = 1.6 \ A$ CharacteristicsInput Capacitance $V_{DS} = 75 \ V, V_{GS} = 0 \ V, f = 1 \ MHz$ Reverse Transfer CapacitanceGate ResistanceCharacteristicsTurn-On Delay TimeRise TimeVDD = 75 \ V, ID = 1.6 \ A, TURN-Off Delay TimeFall Time	Temperature CoefficientID $250 \mu$ A, referenced to $25 °C$ Static Drain to Source On Resistance $V_{GS} = 10 V, I_D = 1.6 A$ Static Drain to Source On Resistance $V_{GS} = 6 V, I_D = 1.4 A$ $V_{GS} = 10 V, I_D = 1.6 A, T_J = 125 °C$ Forward Transconductance $V_{DS} = 10 V, I_D = 1.6 A$ Input Capacitance $V_{DS} = 10 V, I_D = 1.6 A$ Output Capacitance $V_{DS} = 75 V, V_{GS} = 0 V, f = 1 MHz$ Reverse Transfer Capacitance $f = 1 MHz$ Gate Resistance $Q_{DD} = 75 V, I_D = 1.6 A, f = 1.6 A,$	$\begin{array}{c c c c c c c c c c c c c c c c c c c $	$\begin{array}{c c c c c c c c c c c c c c c c c c c $

a) 80 °C/W when mou 1 in<sup>2</sup> pad of 2 oz co



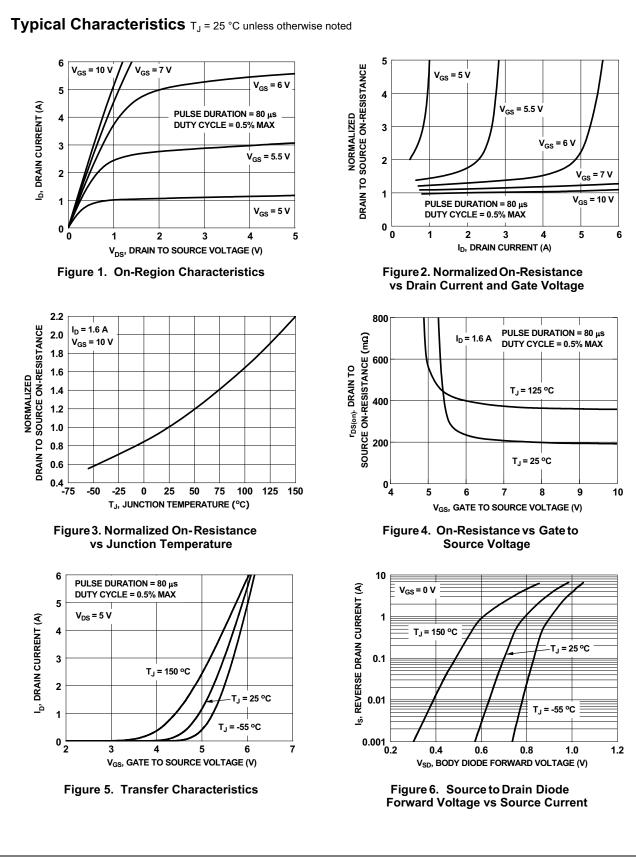
FDN86246 N-Channel PowerTrench<sup>®</sup> MOSFET

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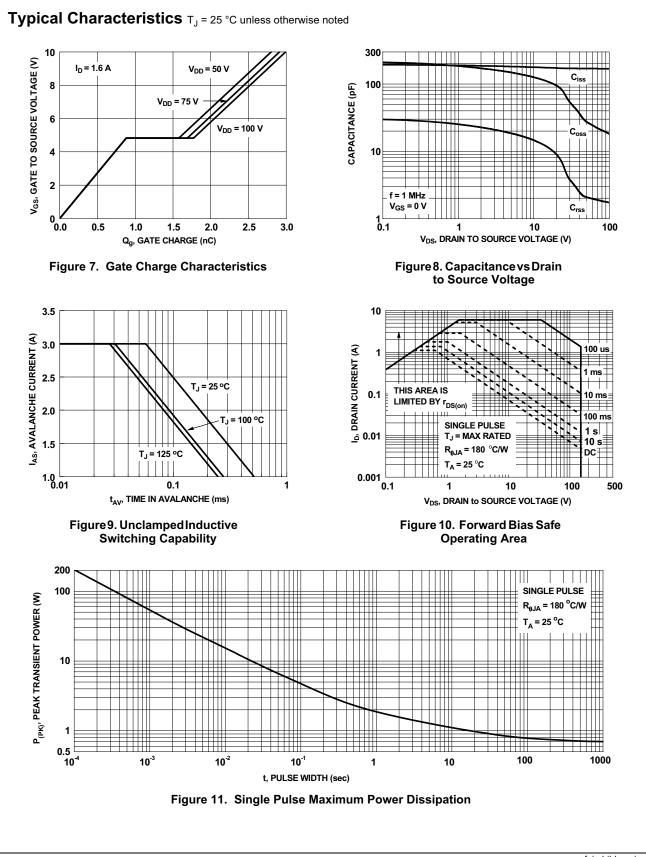
3. Starting T\_J = 25 °C; N-ch: L = 3 mH, I\_{AS} = 3 A, V\_DD = 150 V, V\_{GS} = 10 V.

2. Pulse Test: Pulse Width < 300  $\mu s,$  Duty cycle < 2.0%.



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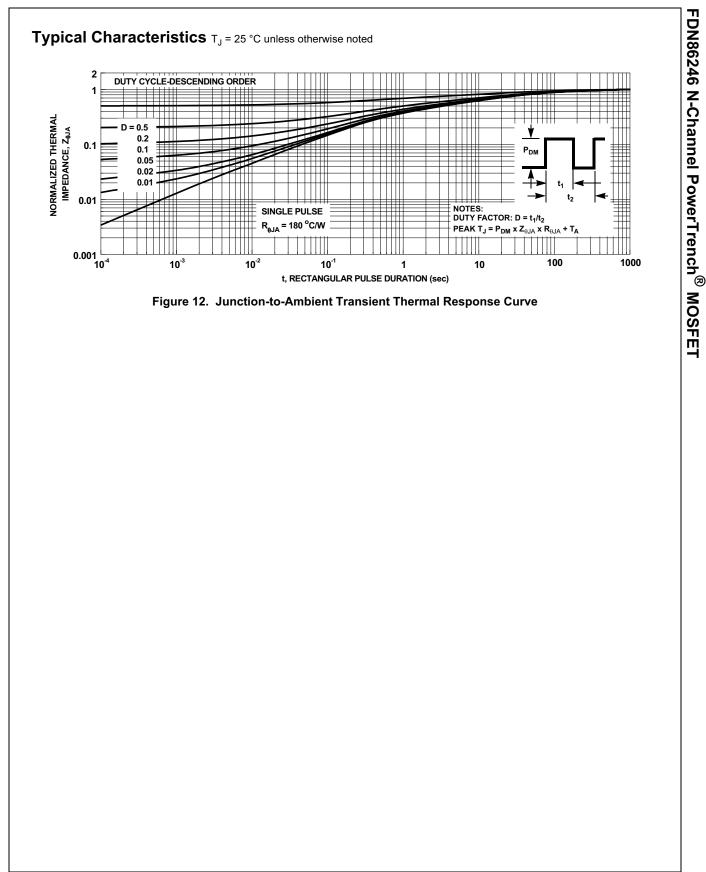
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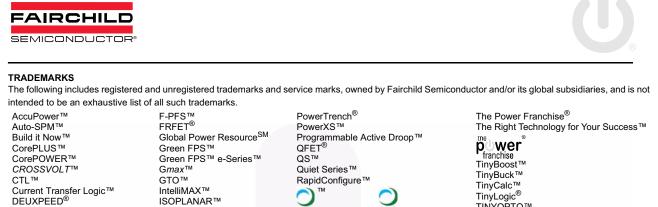


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